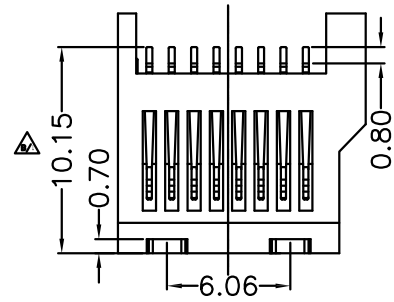
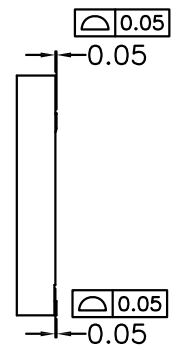
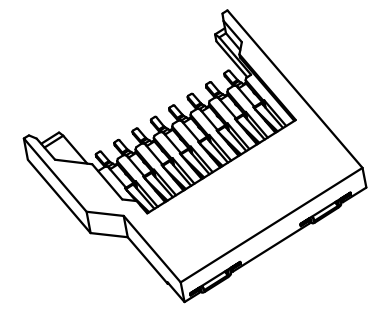
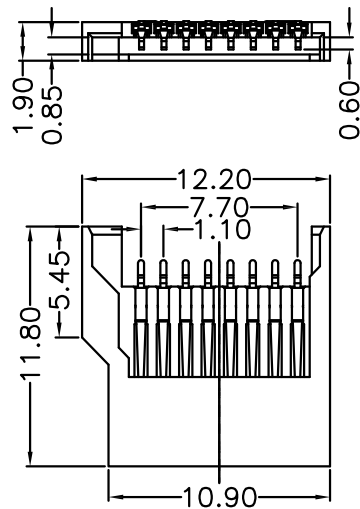


REV.	ECN.NO.	APPD.
A	XXXXXXXXXX	chenyiting



***Electrical Characteristics:**
 Contact Current Rating:0.5 Amperes.
 Dielectric Withstanding Voltage:AC500V r.m.s.
 Insulation Resistance:1000 MΩ Minimum.
 Contact Resistance:100 mΩ Maximum.

***Environmental:**
 Operating Temperature:-25°C~+90°C.

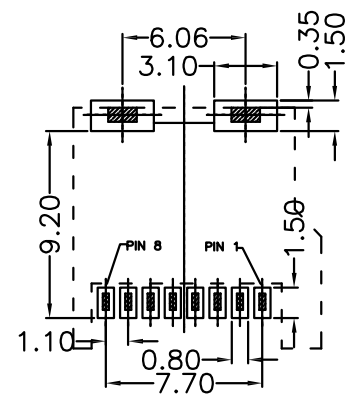
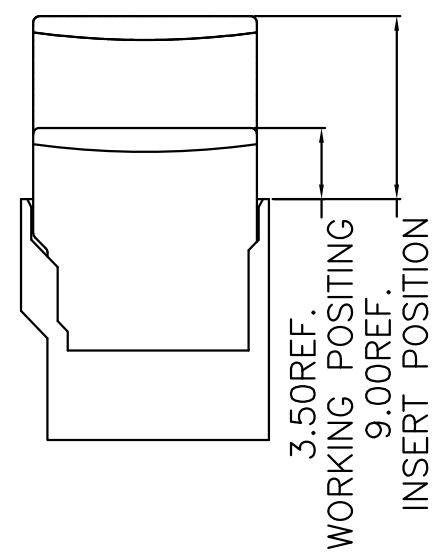
***Environmental:**
 Mating Cycles:5000~10,000 Insertions.

***Mechanical Characteristics:**
 Card Push Insertion/Out Force:1.4kgf. MAX
 Contact Separation Force:0.20kgf Minimum.

***Material:**
 Insulator:HI-Temp Plastic UL 94V-0 Rated.
 Contact:Copper Alloy(t=0.15mm).
 Shell:Stainless Steel(t=0.20mm).
 Spring:SWP.

SD5209-045-G618

G: 半金G/Fu”
 6:LCP黑色



RECOMMENDED P.C.B HOLE LAYOUT COMPONENT SIDE VIEW(TOLERANCE: +/-0.05)

PIN NO.	NAME
1	DAT2
2	CD/DAT3
3	CMD
4	VDD
5	CLX
6	VSS
7	DAT0
8	DAT1

TOLERANCE UNLESS OTHERWISE SPECIFIED		FLW 深圳市华联威电子科技有限公司 HUA LIAN WEI TECHNOLOGY ELECTRONICS CO;LTD.			
.XXX ±0.10	.X ±0.30	.X ±3'			
.XX ±0.20	.XX ±2'				
.X ±0.30					
APPROVED		PART NAME:	TF 卡座 (有开关)		
CHECKED		PART No:	SD5209-045-G618	C	
DRAWN	chenyiting	PROJECTION:	UNIT:	SCALE	SHEET
DATE	2022.10.09		mm	1:1	10F1
				REV.	A